European 3D TSV Summit (Jan 20-22, 2014)
Grenoble - France

Yann Guillou – Event organizer - SEMI
European 3D TSV Summit 2013 (Jan 21-22)

- 1st edition
- 320 attendees from 20 countries
- Sold out exhibition
- Excellent rating & feedback from attendees, exhibitors, sponsors
Conference
Conference
Networking
Building on this success, SEMI is announcing a 2nd edition on Jan 20-22 in Grenoble, France

European 3D TSV Summit: “Application Ready” Theme to Focus on Both Business and Technology Aspects

SEMI to organize the 2nd European 3D TSV Summit

GRENOBLE, France — September 4, 2013 — The latest TSV product developments and achievements will be discussed at the 2nd edition of the SEMI European 3D TSV Summit on January 20-22, 2014 in Grenoble, France. Building on the success of the 1st edition that attracted almost 320 people from 20 countries, the theme of this year’s event is “Application Ready,” addressing 3D TSV from both a business and technology perspective. The latest TSV product developments and achievements — including cost, business models, supply chain, manufacturability and technology aspects — will be addressed by executives and experts from global leading companies.

Executives from design houses, fabless, IDMs, OSATs as well as Equipment and Materials suppliers will present during this unique two-day event. More than 25 speakers will share their views during the plenary presentations as well as ‘round table’ discussions. An exhibition zone will be located at the heart of the venue, enabling companies to showcase their products and services to decision makers. The 3D TSV Summit (www.semi.org/european3DTSYSummit) also includes a unique opportunity to visit the CEA-LETI 300mm TSV clean room. Prior to the event, attendees will be able to prepare their Summit schedule on-site meetings by using a specially developed software tool.

New this year, as an introduction to the event, a Pre-Summit Symposium discussing MEMS and TSV will be held on January 20 in the late afternoon with an invited speaker, roundtable and welcome cocktail.

The event continues addresses the hot and controversial topics related to 3D TSV manufacturing and offers unique networking and promotion opportunities. The European 3D TSV Summit Steering Committee includes executives from: ams AG, BESI, CEA-LETI, EV Group, Fraunhofer IZM, imec, Multitest, Celerion Systems, SPTS, STMicroelectronics, and SUSS Microtec.

Please visit www.semi.org/european3DTSYSummit. Registration and booking for exhibition space is now open. Sponsorship packages are also available now. For additional information, contact Yann Guillou from SEMI Europe Grenoble Office (yguillou@semi.org).
European 3D TSV Summit 2014 (Jan 20-22)

The Power of [Integration]

European 3D TSV Summit
Application Ready

EXHIBITION & CONFERENCE January 20-22, 2014
Grenoble (France)
European 3D TSV Summit 2014 is:

• At the same location, same venue
• At similar dates
• Global event: Europe, US, Asia
• Attracting executive speakers from leading companies
• Featuring IDMs, Fabless, Foundries, R&D centers, equipment and material makers, market analysts
• Interactive with panel discussions
• Proposing a unique TSV for MEMS session
• Hosting a CATRENE 3D session
• Enlarged exhibiting show floor
• Offering complementary one on one business meeting
• Offering a CEA-LETI 300mm TSV clean room visit
Schedule at a glance

- Monday Jan 20\textsuperscript{th} late afternoon: Pre Summit Symposium
  - TSV for MEMS session
  - Keynote followed by a panel discussion
  - Closing networking cocktail
- Tuesday Jan 21\textsuperscript{st}:
  - Full conference day: Market, Technologies, CoO, Manufacturing
  - Exhibition
  - One-on-one business meetings
  - Gala dinner
- Wednesday Jan 22\textsuperscript{nd}:
  - Conference on the morning: Supply chain, Products
  - One-on-one business meetings
  - CATRENE 3D Session
  - CEA-LETI 300mm TSV clean room tour
Conference program will feature executive speakers from:

- AMS AG
- APPLIED MATERIALS
- CEA-LETI
- DISCO
- EV GROUP
- FRAUNHOFER-IZM
- GARTNER
- GLOBALFOUNDRIES
- IBM
- IME
- IMEC
- MULTITEST
- OERLIKON SYSTEMS
- SILEX
- SPTS
- STATS ChipPAC
- STMICROELECTRONICS
- SUSS MICROTEC
- TOKYO ELECTRON
- TRONICS
- TSMC
- YOLE DEVELOPPEMENT
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Keynotes

• GLOBALFOUNDRIES
  – David McCann
  – Senior Director, Technical Business Operations, Packaging and Central Engineering

• STMicroelectronics
  – Joel Hartmann
  – eVP Front-End Manufacturing and Process R&D, Embedded Processing Solutions Segment

• TSMC
  – Name TBC
  – VP
Special Focus: Market Outlook Session

• 3D Market Supply Chain Forecast 2014-2018
  – Mark Stromberg, Principal Analyst
  – GARTNER

• 3D Packaging Market Trends and Applications
  – Rozalia Beica, CTO Advanced Packaging and Manufacturing Business Unit
  – Yole Developpement
Some invited presentations...

• Extreme High Rate Via Reveal Etch Processes Targeting Improved COO
  – Kevin Crofton, COO & eVP - David Butler, VP Marketing
  – SPTS

• Cost-Effective Platform for Implementation, Prototyping, and Manufacturing of Heterogeneous 2.5D/3DICs
  – Dim-Lee Kwong, Executive Director
  – IME

• Total solution for TSV wafer thinning and dicing
  – Karl Priewasser, eVP
  – DISCO HI-TEC EUROPE GmbH
As well as...

• New Developments in 2.5/3D Integration
  – Raj Pendse, VP and Chief Marketing Officer
  – STATS ChipPAC

• 2.5D and 3D application readiness – through the lens of an equipment maker
  – Sesh Ramaswami, Senior Director Strategy, Silicon Systems Group
  – Applied Materials

• and more presentations from:
  – Martin Schrems, Director or R&D, ams AG
  – Eric Beyne, director Advanced Packaging and Interconnect, imec
  – Jurgen Wolf, department head of HDI WLP /ASSID, Fraunhofer-IZM
  – Herve Ribot, head of 3D, CEA-LETI
  – Paul Lindner, CTO, EV Group
  – Steve Golovato, Director Dry Process Technology, TEL-NEXX
  – ...
Exhibition

- 27 turn-key booths
- Pre Summit Symposium cocktail as well as all breaks and lunch will be on the show floor.
- 1st edition was sold out
One-on-one Business Meeting

• Complementary service
• High value networking
• Possibility to schedule in advance 25 min meetings at the show
• How? Once registered:
  – Connect to the business meeting platform
  – Check the attendee list
  – Send an invitation to the people you identified
  – Get his answer: Either he accepts, rejects or propose a new time
They are supporting the event

• Contact me if interested by our sponsorships
See you in Grenoble on January

Grenoble – 3D by Nature
Lucky Draw

1 iPad mini to win
And the winner is: ....